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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

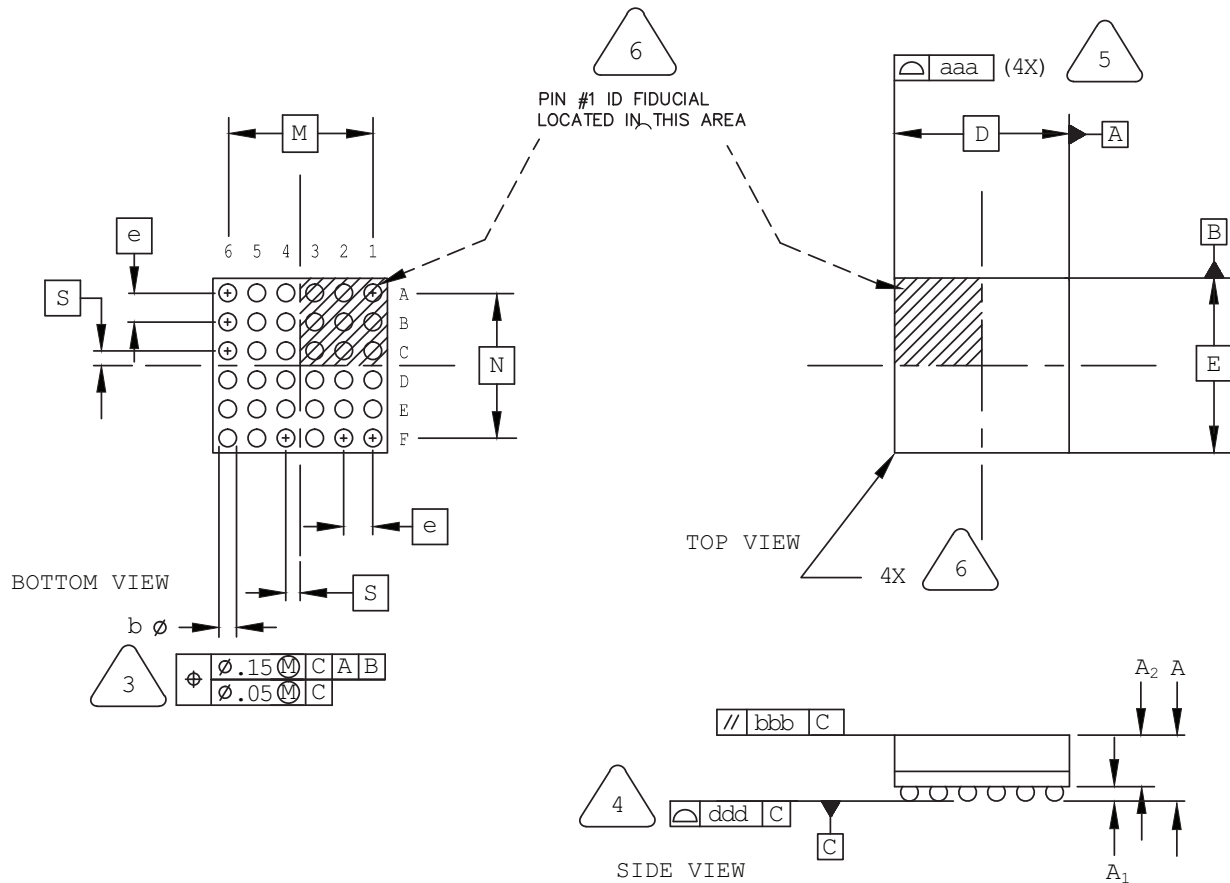
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	256
Number of Gates	-
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 90°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lx256v-35f484c

36-Ball ucfBGA Package: iCE40 Ultra™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

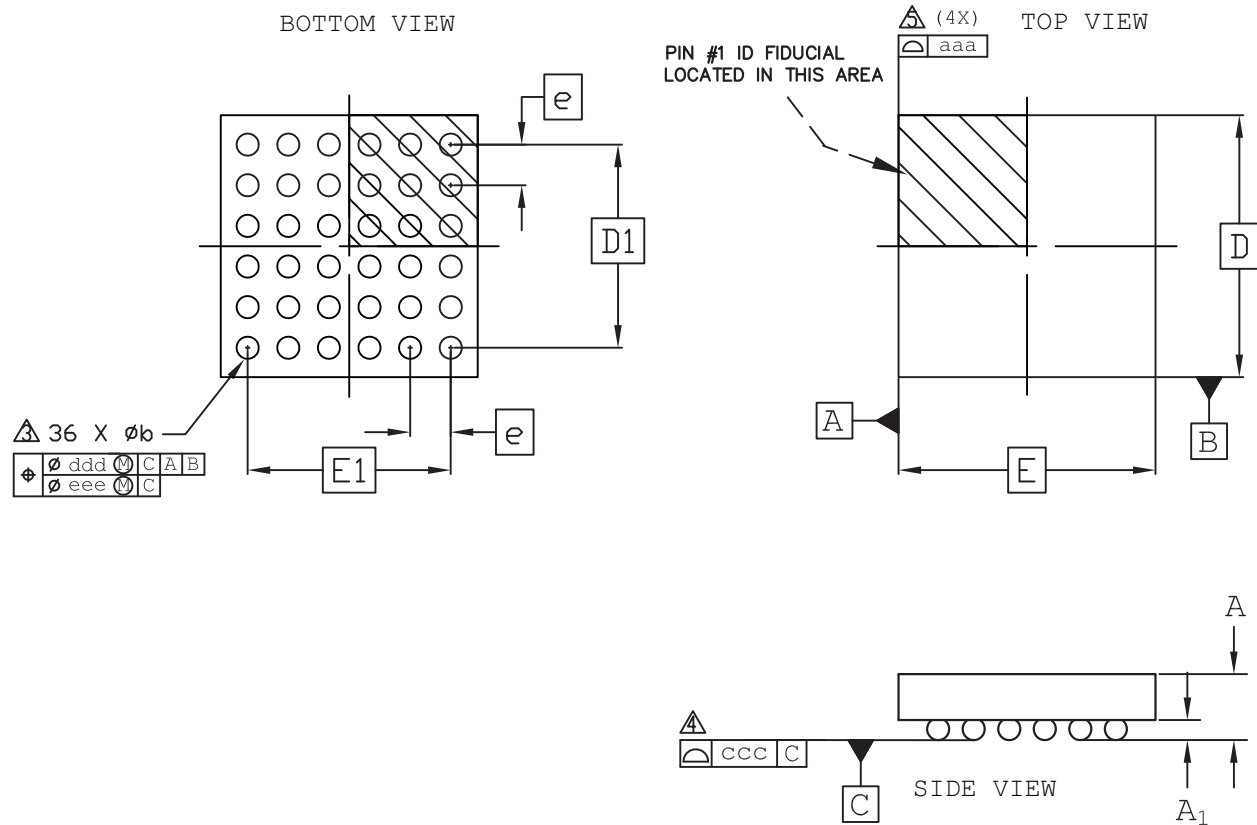
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
- 4 PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	0.81	0.91
A1	0.12	-	-
A2	-	-	0.70
D/E	2.50 BSC		
M/N	2.00 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

36-Ball WLCS Package Option 3: LIFMD™

Dimensions in Millimeters



NOTES:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

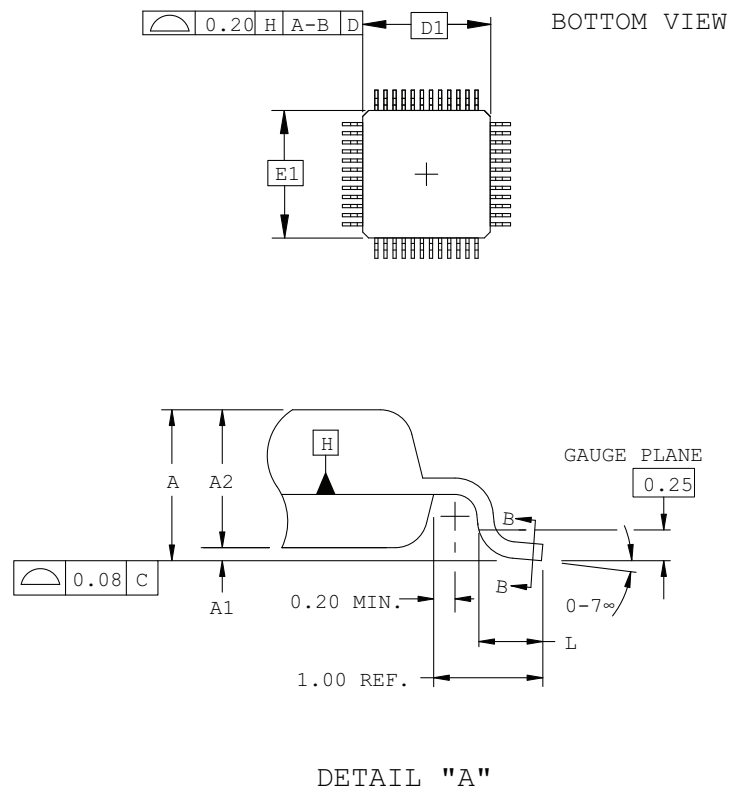
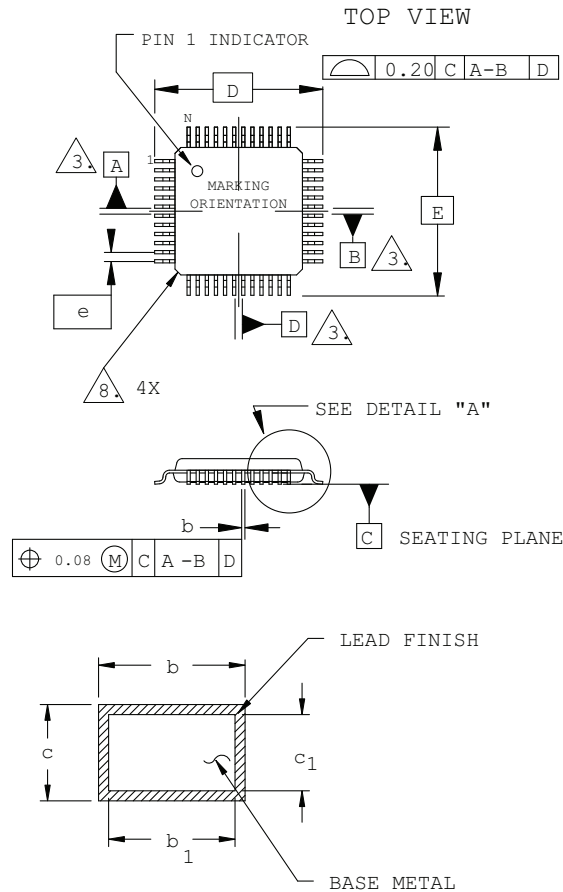
△ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].

△ PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

△ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

48-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters



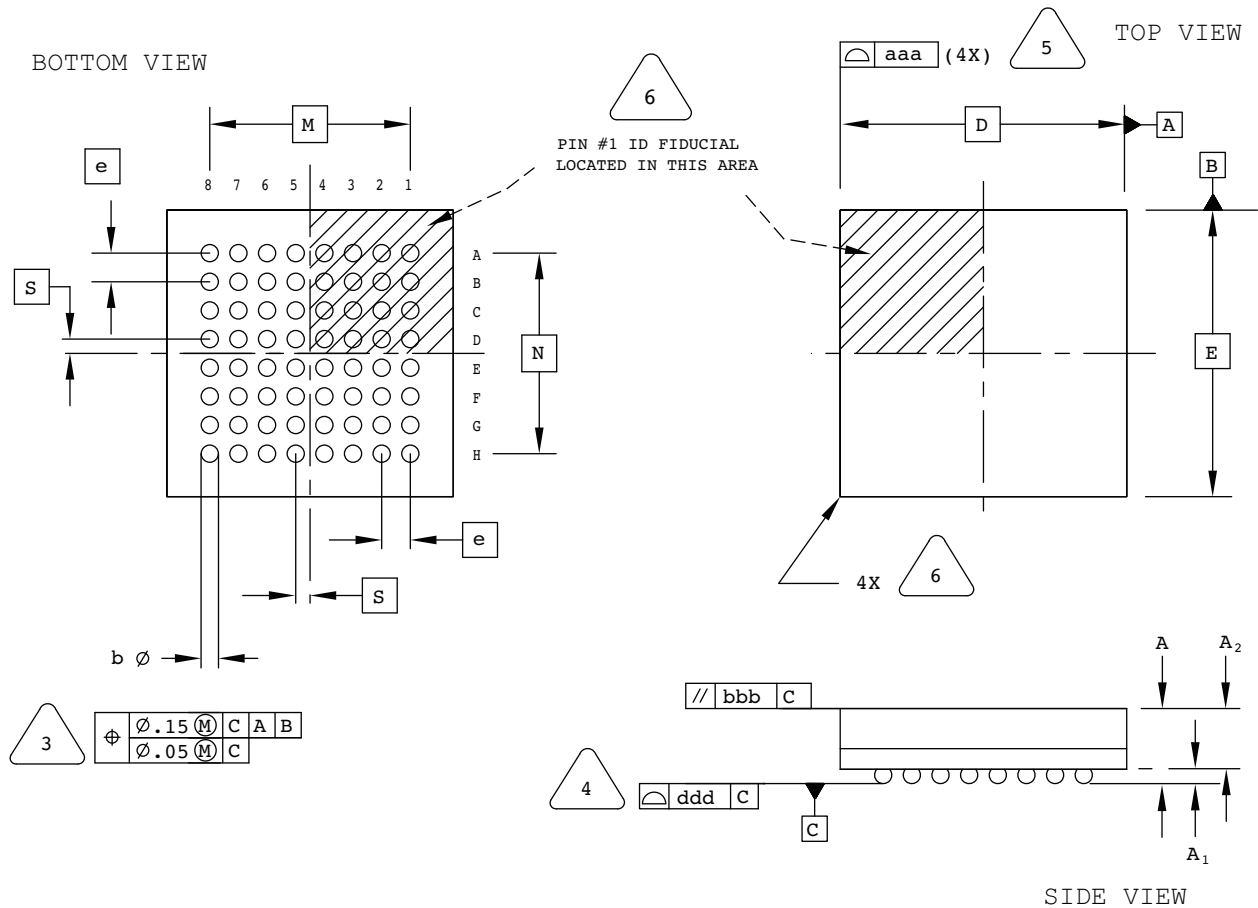
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
N	48		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

64-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



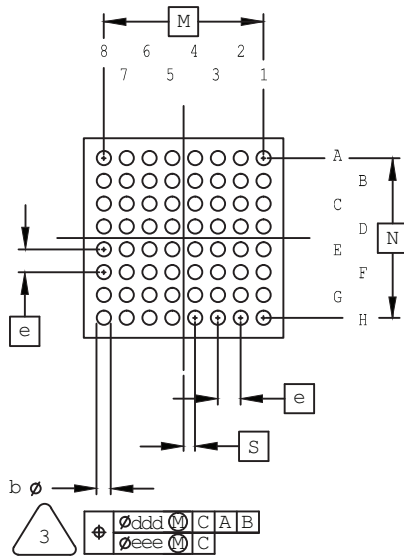
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.15	-	-
A2	-	-	0.85
D/E	5.00 BSC		
M/N	3.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

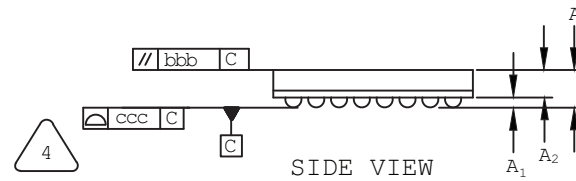
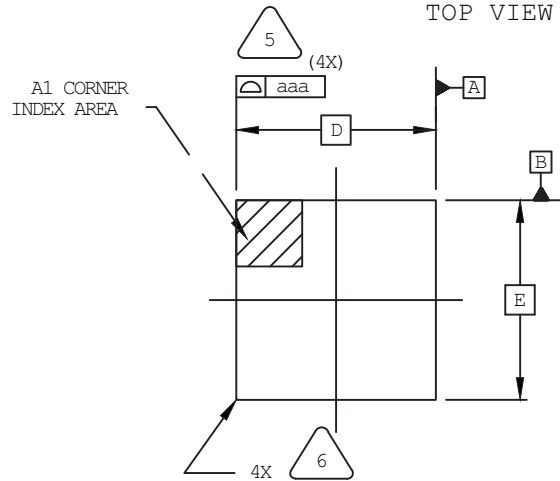
64-Ball ucfBGA Package

Dimensions in Millimeters

BOTTOM VIEW



TOP VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

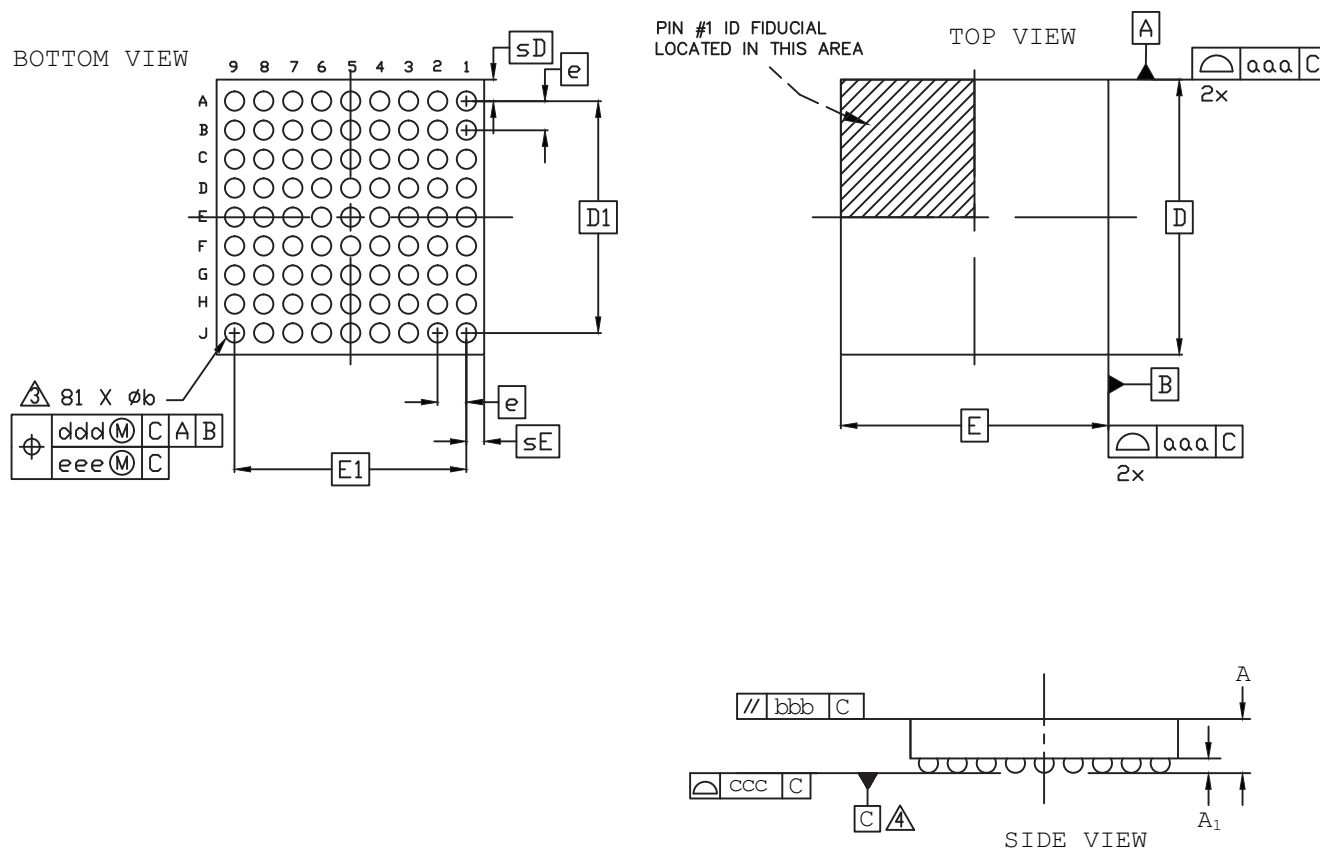


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	–	–	1.00
A1	0.11	–	–
A2	0.62	–	–
D/E	3.50 BSC		
M/N	2.80 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.08		

81-Ball WLCS Package

Dimensions in Millimeters



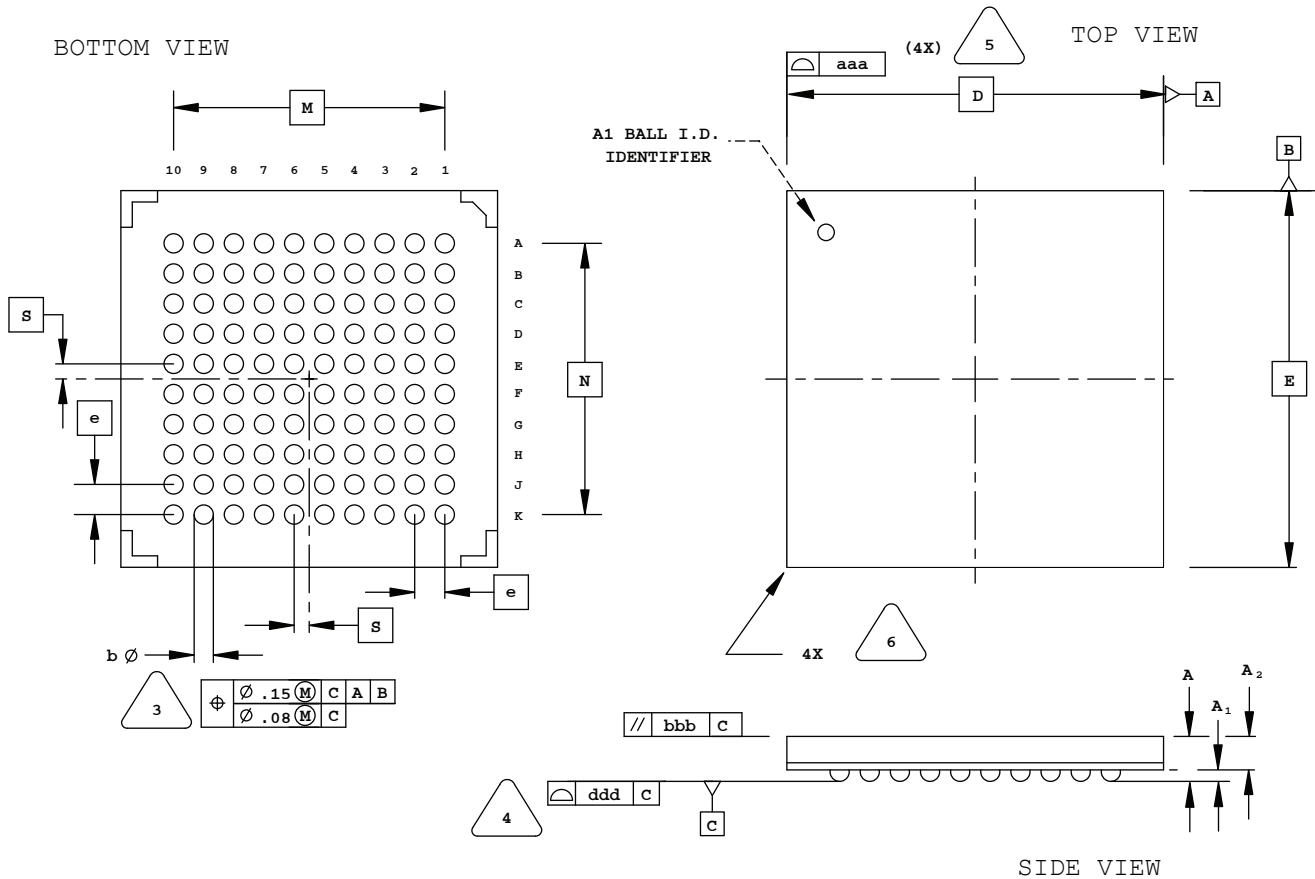
Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- Δ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
- Δ PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	0.510	0.543	0.567
A1	0.167	0.196	0.225
b	0.239	0.266	0.319
D	3.797 BSC		
E	3.693 BSC		
D1	3.20 BSC		
E1	3.20 BSC		
e	0.40 BSC		
sD	-	0.299	-
sE	-	0.247	-
aaa	0.025		
bbb	0.060		
ccc	0.030		
ddd	0.015		
eee	0.050		

100-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES
PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE
MAXIMUM SOLDER BALL DIAMETER,
PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED
TO EACH SIDE OF THE PACKAGE BODY.

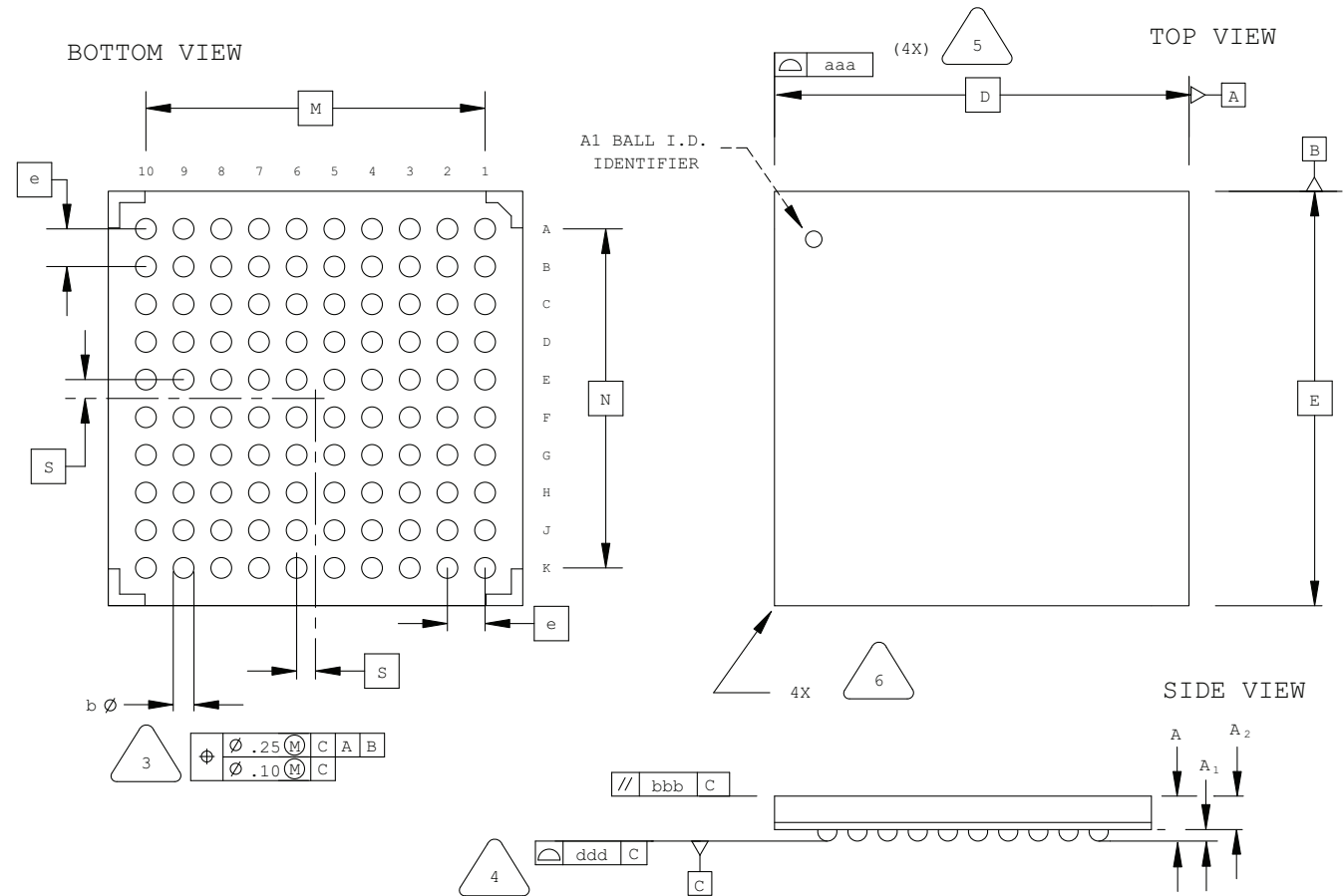


EXACT SHAPE AND SIZE OF THIS FEATURE
IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.40	1.50
A1	0.31	0.36	0.41
A2	0.99	1.04	1.09
D/E	10.00 BSC		
M/N	7.20 BSC		
S	0.40 BSC		
b	0.40	0.46	0.52
e	0.80 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.12

100-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

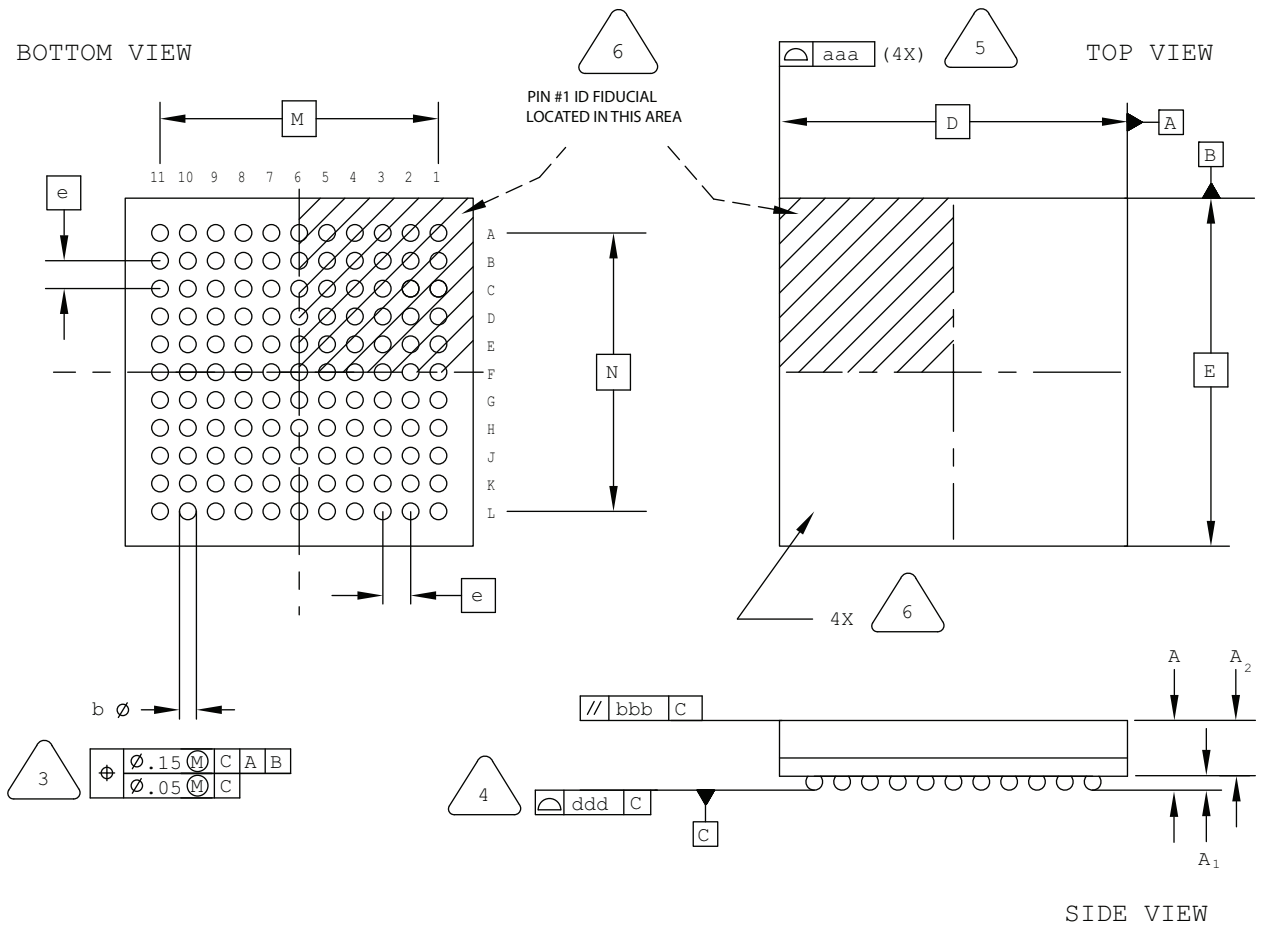
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
- 4 PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.50	1.70
A1	0.30	0.50	0.70
A2	1.10 REF		
D/E	11.00 BSC		
M/N	9.00 BSC		
S	0.50 BSC		
b	0.40	0.55	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

121-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]

4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

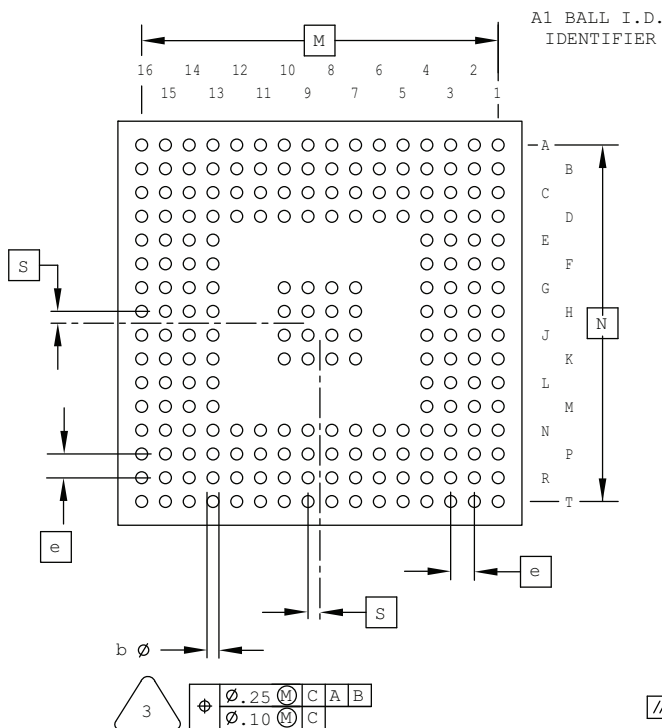
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	5.00 BSC		
M/N	4.00 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10

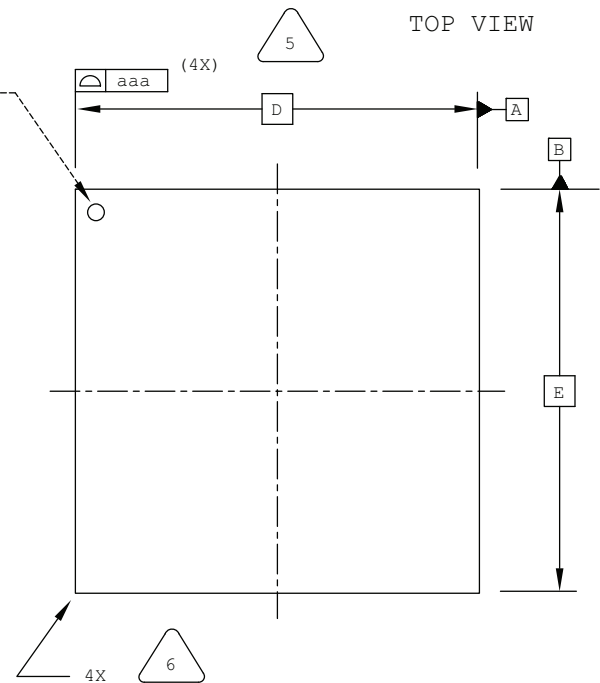
208-Ball ftBGA Package

Dimensions in Millimeters

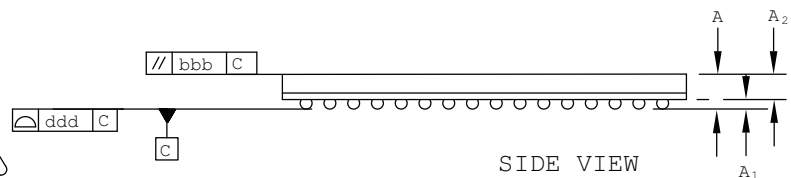
BOTTOM VIEW



TOP VIEW



SIDE VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

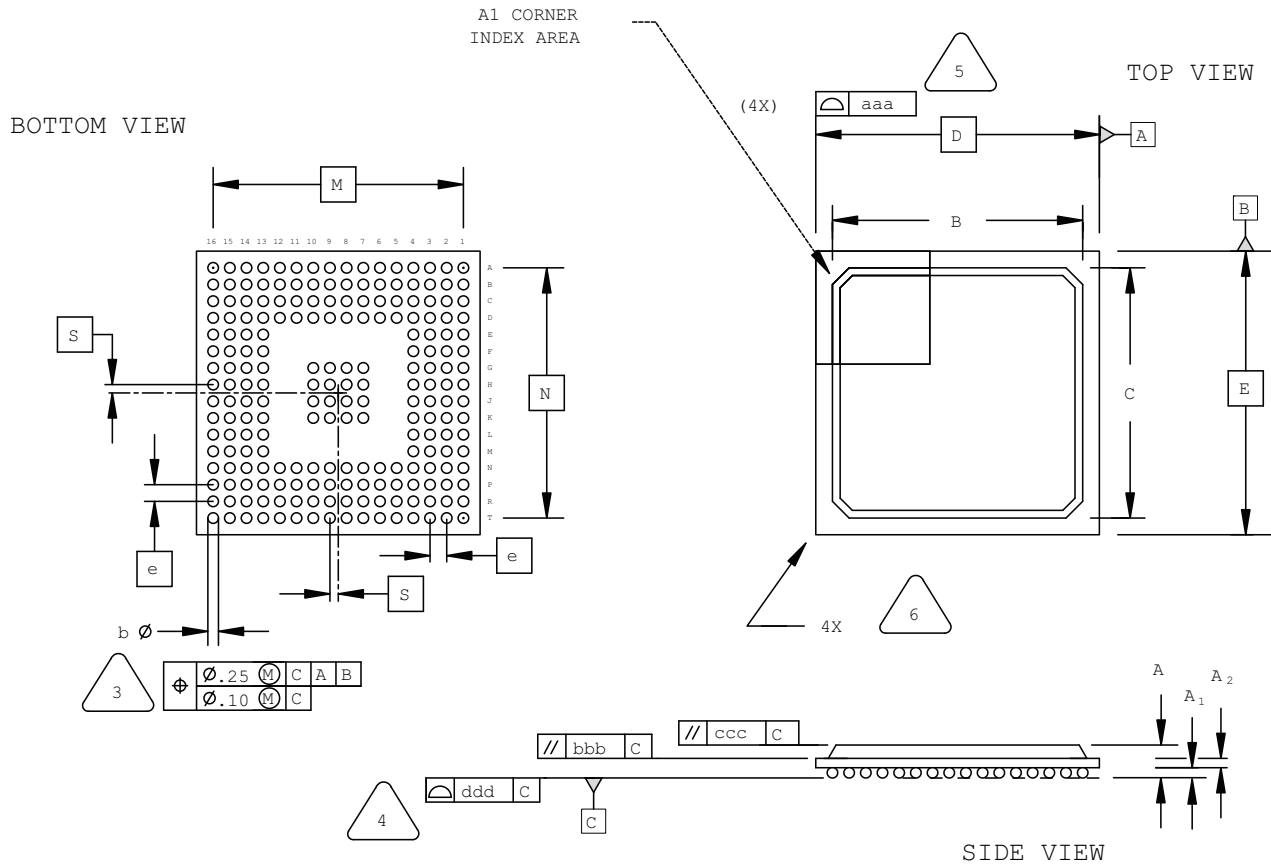


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.40	1.55
A1	0.30	-	-
A2	-	-	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.0 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12

208-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{C}$



PRIMARY DATUM $\boxed{C}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

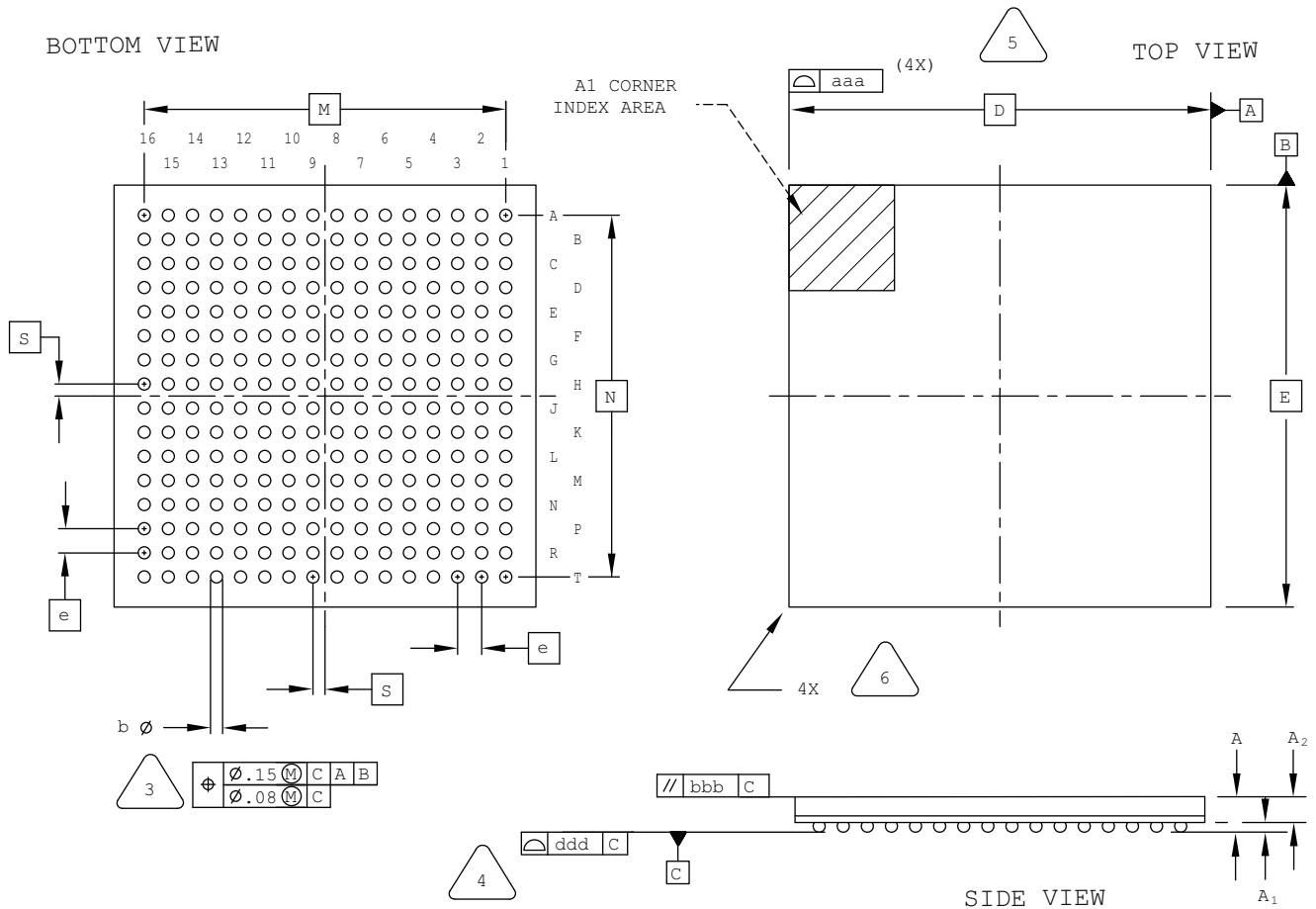


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

256-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



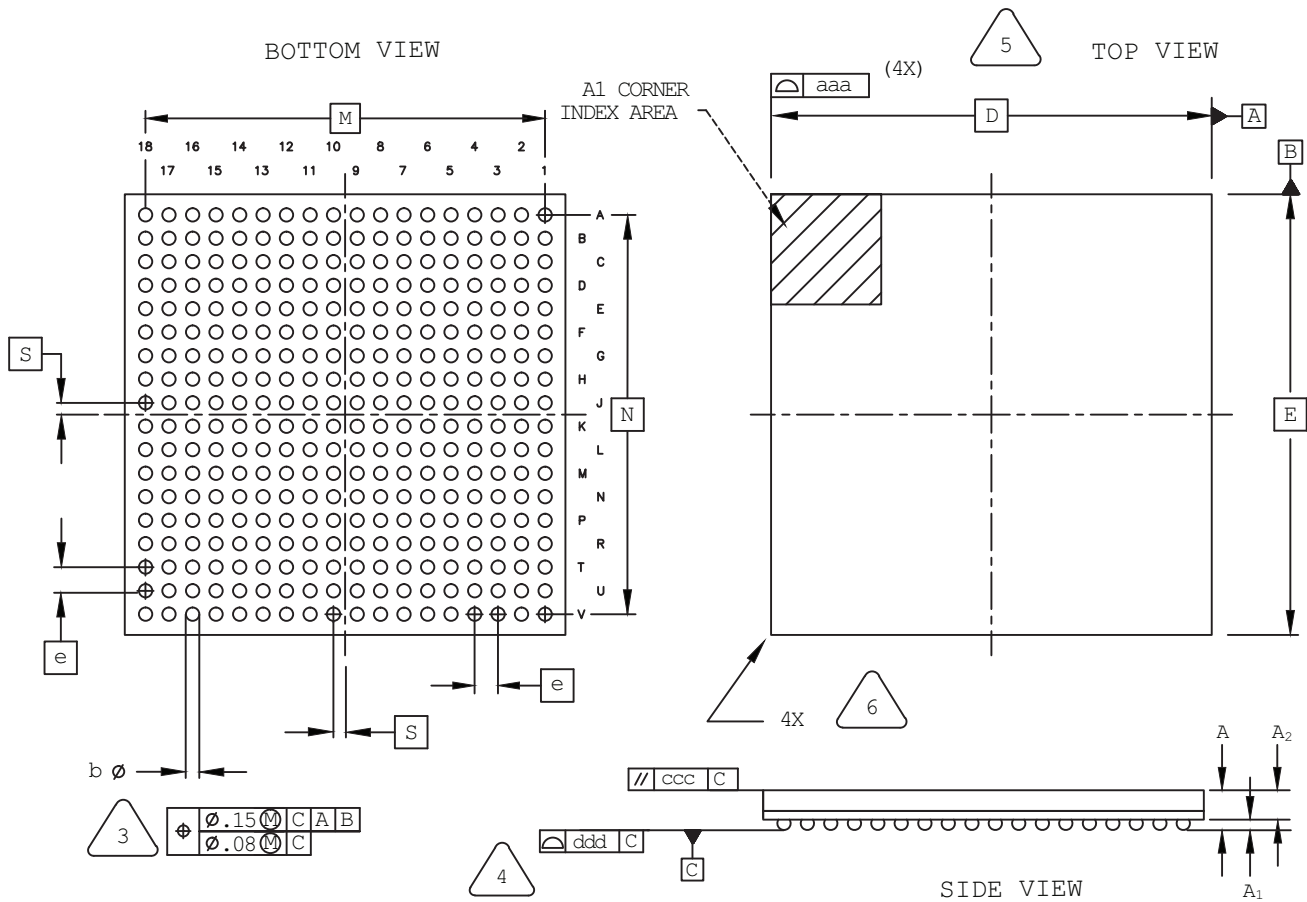
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

7. REFERENCE JEDEC MO-275, VARIATION JJAB-2.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.25	-	-
A2	0.65	-	-
D/E	14.0 BSC		
M/N	12.0 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
bbb	-	-	0.20
ddd	-	-	0.20

324-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

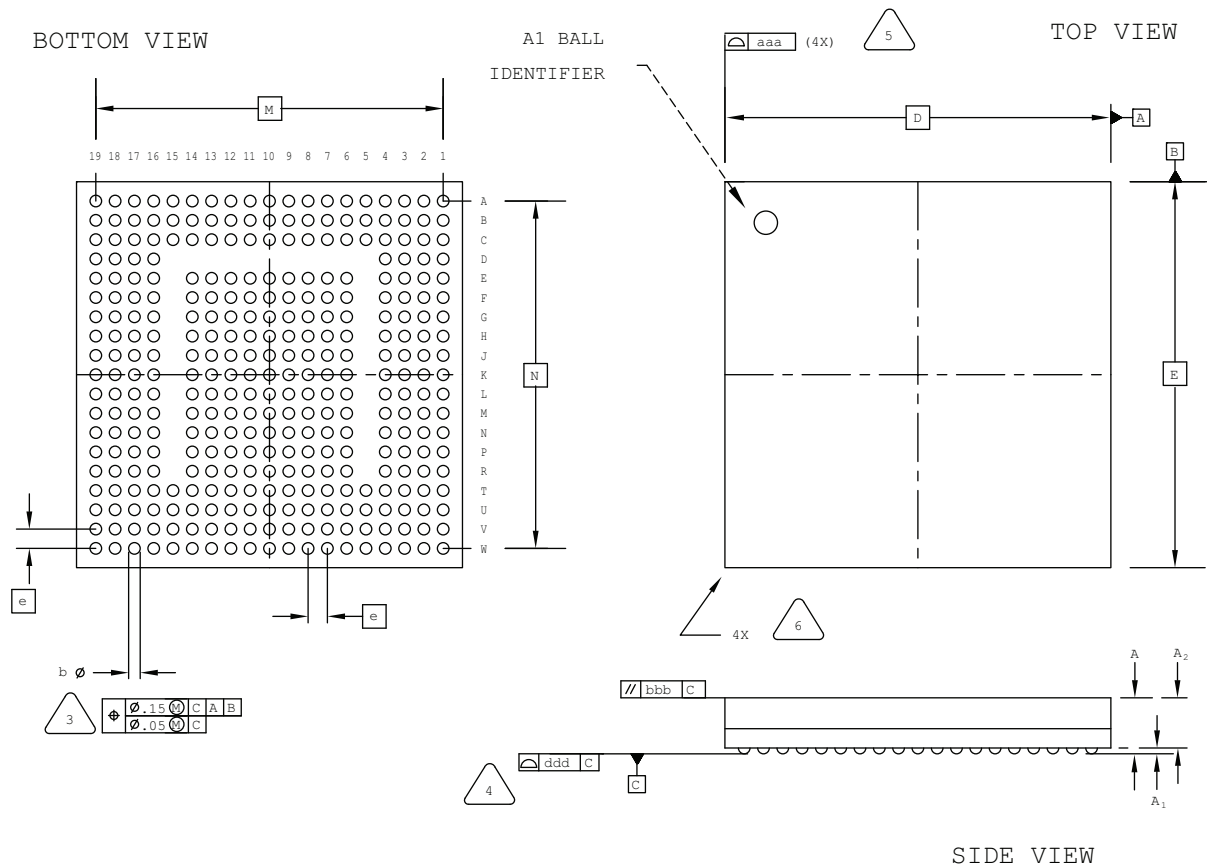


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.25	0.35	-
A2	0.80	1.00	-
D/E	15.0 BSC		
M/N	13.6 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
e	0.80 BSC		
aaa	-	-	0.15
ccc	-	-	0.20
ddd	-	-	0.20

328-Ball csBGA Package

Dimensions in Millimeters



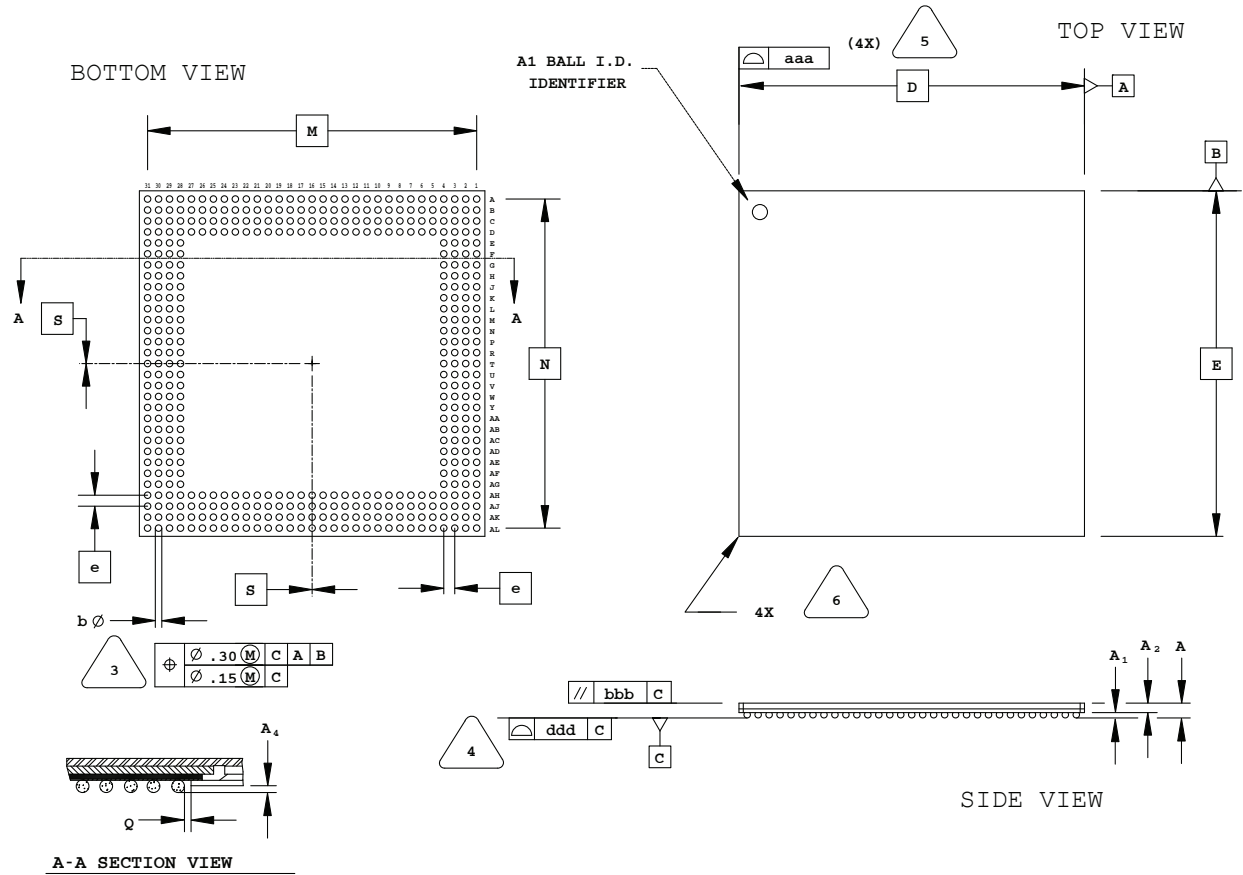
NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

SYMBOL	MIN.	NOM.	MAX.
A	1.05	1.35	1.50
A1	0.15	-	-
A2	-	-	1.20
D/E	10.0 BSC		
M/N	9.00 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

432-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

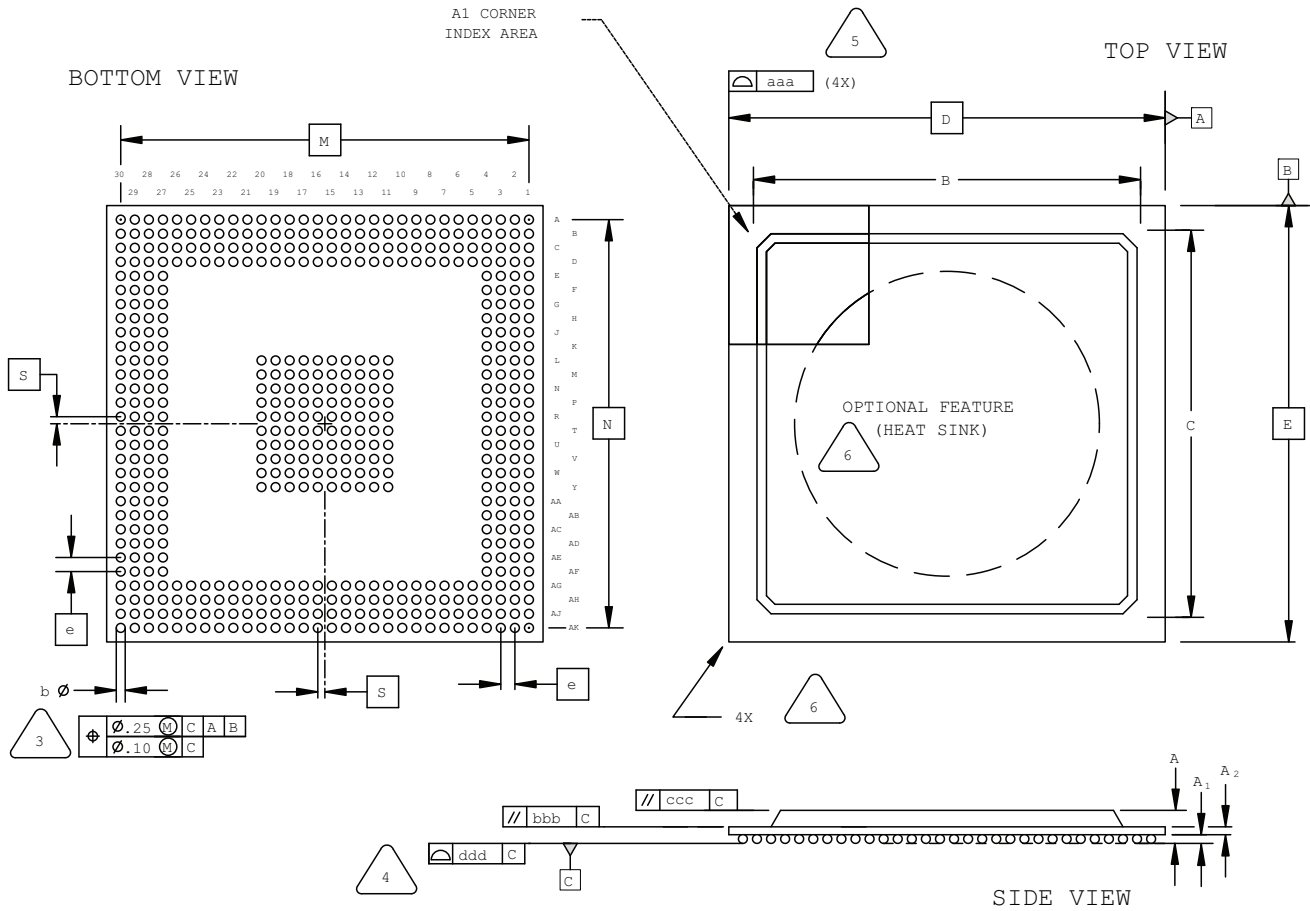


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	40.00 BSC		
M/N	38.10 BSC		
S	0.00 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

516-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

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- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

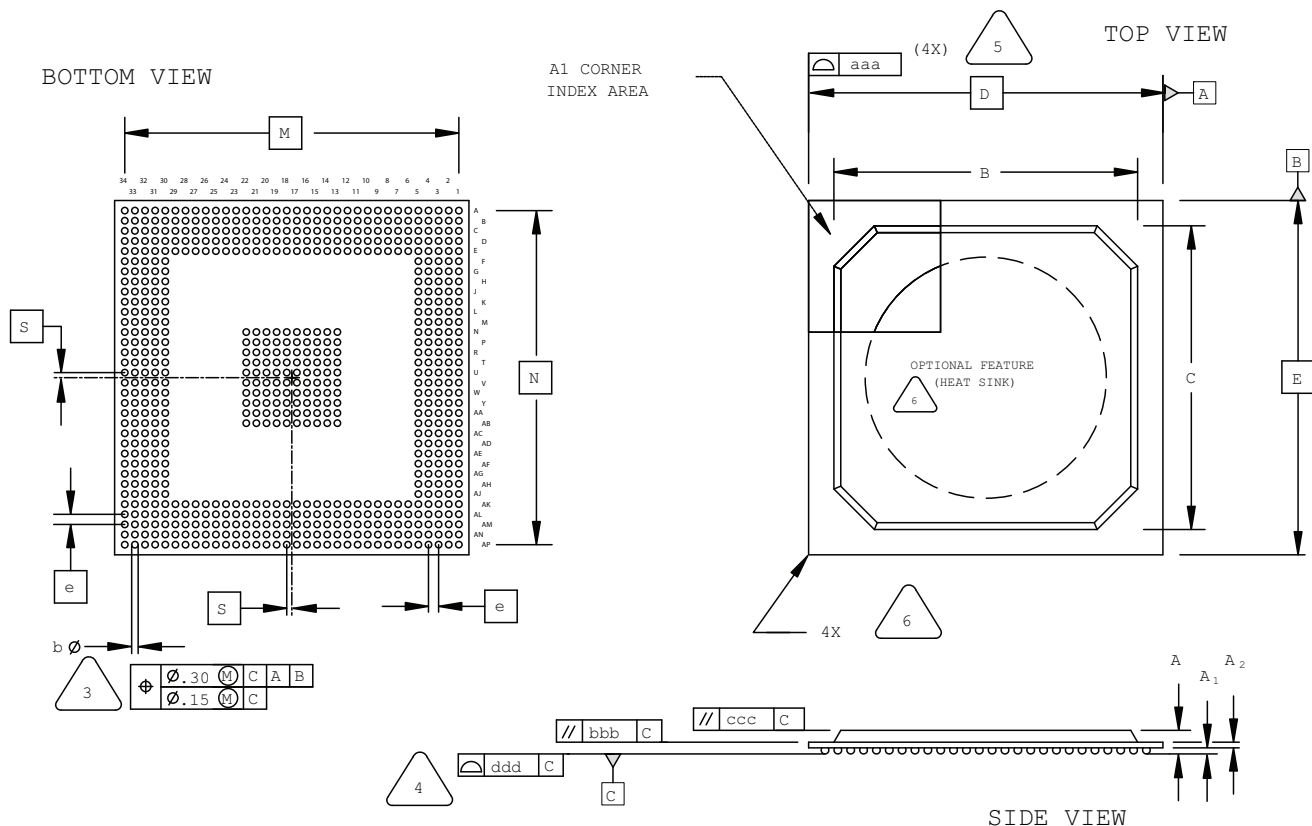


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

680-Ball fpBGA Package

(with or without Internal Heat Spreader)
Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

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DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

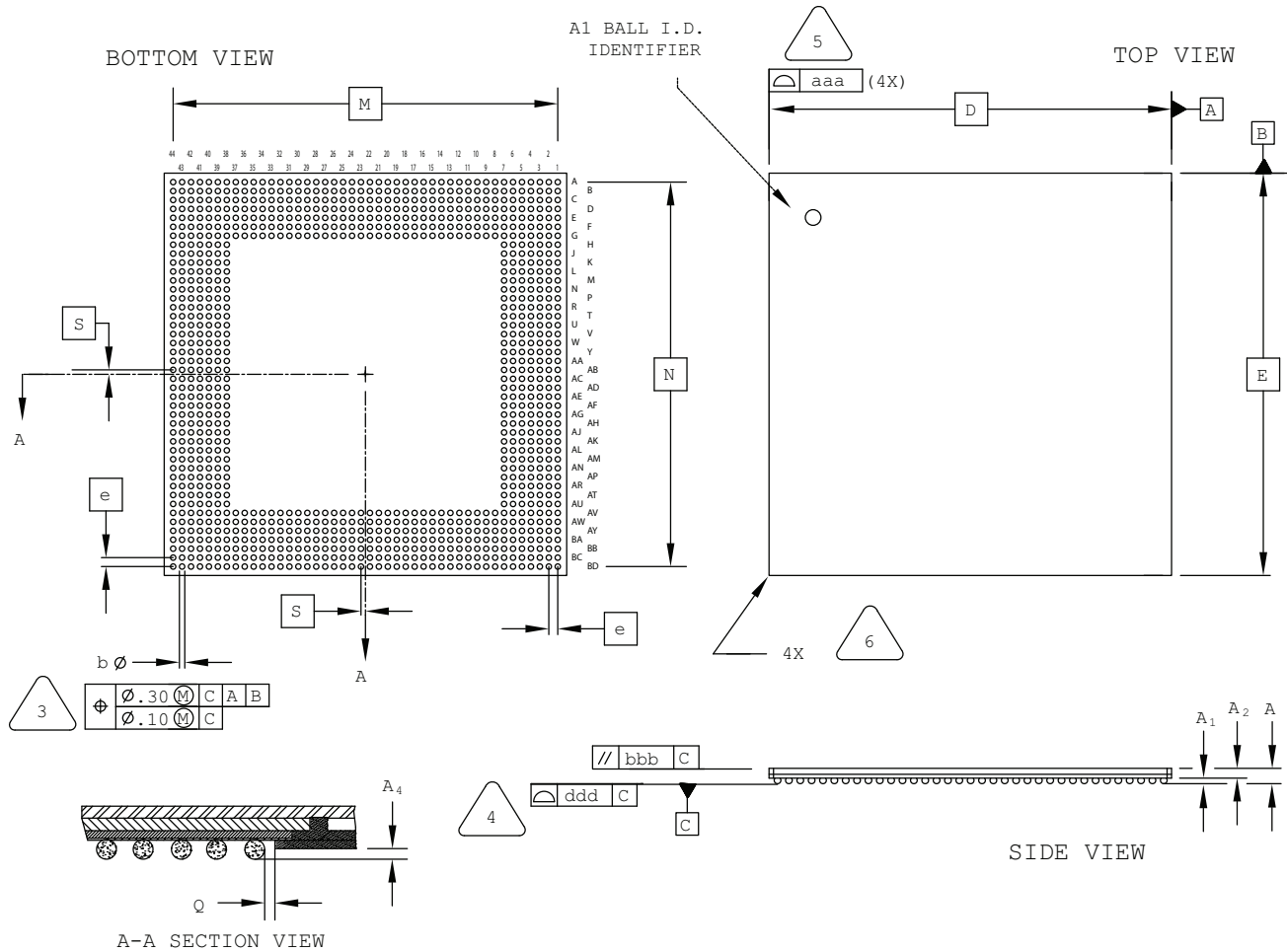


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

1036-Ball ftSBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

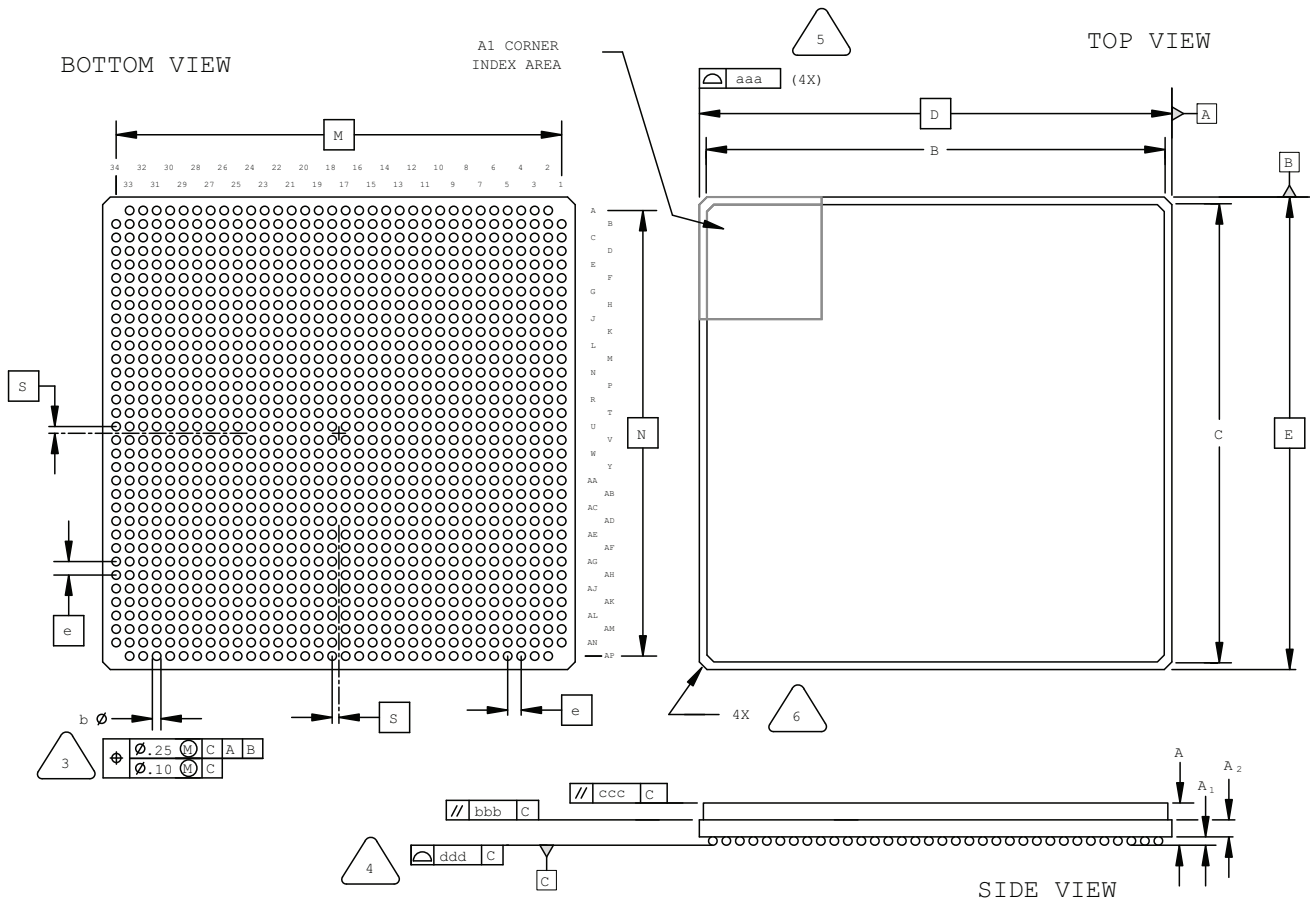
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2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	45.00 BSC		
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
e	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20

1152-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	4.00	4.60	5.20
A1	0.30	0.50	0.70
A2	1.40 REF		
B/C	33.10	34.00	34.90
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

Revision History

Date	Version	Change Summary
March 2017	5.4	Added ispMACH 4000 to 100-Pin TQFP Package Option 1: MachXO2, MachXO™, ispMACH® 4000.
		Added 121-Ball caBGA Package (9x9 mm Body).
December 2016	5.3	Updated “32-Pin QFNS Package” headings to “32-Pin QFN Package”.
		Added 32-Pin QFN Package Option 3: MachXO2 SG32C.
		Added 30-Ball WLSC Package.
		Added iCE40 UltraPlus and MachXO2 to 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2.
		Added 484-Ball caBGA Package.
June 2016	5.2	Updated 285-ball csfBGA package outline drawing.
		Added 36-Ball WLCS Package Option 3: LIFMD™.
		Fixed typo in 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2.
		Added 64-Ball ucfBGA Package.
		Added 80-Ball ctfBGA Package.
		Added 81-Ball csfBGA Package.
February 2015	5.1	Added 36-Ball ucfBGA Package: iCE40 Ultra.
		Updated 36-Ball ucBGA Package heading to 36-Ball ucBGA Package Option 1.
		Updated 48-Pin QFN Package Option 2: L-ASC10 heading to 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra.
January 2015	5.0	Added 16-Ball WLCS Package Option 2: iCE40 UltraLite.
		Updated 16-Ball WLCS Package heading to 16-Ball WLCS Package Option 1: iCE40 LP.
October 2014	4.9	Updated 48-Pin QFN Package heading and moved the section after 48-Pin QFN Package Option 1 (previously Option 2).
	4.8	Removed 20-Ball WLCS Package.
	4.7	Updated 121-Ball csfBGA Package. Revised M/N dimension.
September 2014	4.6	Updated 84-Pin QFN Package. Revised pin numbers from A36 and B27 to A37 and B28.
August 2014	4.5	Updated 16-Ball WLCS Package. Changed second E to e in REF. column.
		Updated 36-Ball WLCS Package Option 1: iCE40 Ultra heading.
		Added 36-Ball WLCS Package Option 2: MachXO3.
		Added 81-Ball WLCS Package.
		Added 121-Ball csfBGA Package.
		Added 256-Ball csfBGA Package.
		Added 324-Ball caBGA Package.
		Added 324-Ball csfBGA Package.
		Added 400-Ball caBGA Package.
		Updated 84-Pin QFN Package. Revised dimension “b” maximum value.
		Updated 256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2. Revised dimension “A” values.